



DIM400XSM45-TS001

Single Switch IGBT Module

DS6149-6 August 2023 (LN42791)

FEATURES

Replaces DS6149-5

- 10.2kV Isolation
- 10us Short Circuit Withstand
- High Thermal Cycling Capability
- High Current Density Enhanced DMOS SPT
- Isolated AlSiC Base With AlN Substrates
- Lead Free Construction

APPLICATIONS

- High Reliability Inverters
- **Motor Controllers**
- **Traction Drives**
- Choppers

The Powerline range of high power modules includes half bridge, chopper, dual, single and bi-directional switch configurations covering voltages from 1200V to 6500V and currents up to 2400A.

The DIM400XSM45-TS001 is a single switch 4500V, n-channel enhancement mode, insulated gate bipolar transistor (IGBT) module. The IGBT has a wide reverse bias safe operating area (RBSOA) plus 10µs short circuit withstand. This device is optimised for traction drives and other applications requiring high thermal cycling capability.

The module incorporates an electrically isolated base plate and low inductance construction enabling circuit designers to optimise circuit layouts and utilise grounded heat sinks for safety.

ORDERING INFORMATION

Order As:

DIM400XSM45-TS001

Note: When ordering, please use the complete part number

KEY PARAMETERS

V_{CES}		4500\
V _{CE(sat)}	* (typ)	2.5V
Ic	(max)	400A
I _{C(PK)}	(max)	A008

^{*} Measured at the auxiliary terminals

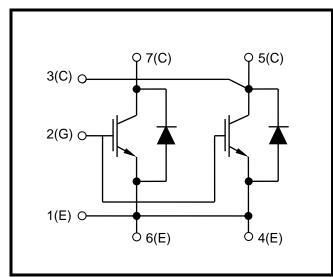


Fig. 1 Circuit configuration



Fig. 2 Package

ABSOLUTE MAXIMUM RATINGS

Stresses above those listed under 'Absolute Maximum Ratings' may cause permanent damage to the device. In extreme conditions, as with all semiconductors, this may include potentially hazardous rupture of the package. Appropriate safety precautions should always be followed. Exposure to Absolute Maximum Ratings may affect device reliability.

T_{case} = 25°C unless stated otherwise

Symbol	Parameter	Test Conditions	Max.	Units
Vces	Collector-emitter voltage	V _{GE} = 0V	4500	V
V _{GES}	Gate-emitter voltage		±20	V
lc	Continuous collector current	T _{case} = 90°C	400	Α
I _{C(PK)}	Peak collector current	1ms, T _{case} = 115°C	800	Α
P _{max}	Max. transistor power dissipation	$T_{case} = 25^{\circ}C, T_{j} = 125^{\circ}C$	4.2	kW
l²t	Diode I ² t value	$V_R = 0$, $t_p = 10$ ms, $T_j = 125$ °C	50	kA ² s
V _{isol}	Isolation voltage – per module	Commoned terminals to base plate. AC RMS, 1 min, 50Hz	10.2	kV
Q_{PD}	Partial discharge – per module	IEC1287, V ₁ = 6900V, V ₂ = 5100V, 50Hz RMS	10	рС

THERMAL AND MECHANICAL RATINGS

Internal insulation material:

Baseplate material:

Creepage distance:

Clearance:

CTI (Comparative Tracking Index):

AIN

AISiC

56mm

26mm

>600

Symbol	Parameter	Test Conditions	Min	Тур.	Max	Units
R _{th(j-c)}	Thermal resistance – transistor	Continuous dissipation - junction to case	-	-	24	°C/kW
R _{th(j-c)}	Thermal resistance – diode	Continuous dissipation - junction to case	-	ı	48	°C/kW
R _{th(c-h)}	Thermal resistance – case to heatsink (per module)	Mounting torque 5Nm (with mounting grease)	-	1	8	°C/kW
T _j	Junction temperature	Transistor	-	-	125	°C
		Diode	-	-	125	°C
T _{stg}	Storage temperature range	-	-40	ı	125	°C
	Screw torque	Mounting – M6	-	ı	5	Nm
		Electrical connections – M4	-		2	Nm
		Electrical connections – M8	-	-	10	Nm

ELECTRICAL CHARACTERISTICS

 T_{case} = 25°C unless stated otherwise.

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
I _{CES}	Collector cut-off current	V _{GE} = 0V, V _{CE} = V _{CES}			1	mA
		V _{GE} = 0V, V _{CE} = V _{CES} , T _{case} = 125°C			20	mA
I _{GES}	Gate leakage current	V _{GE} = ± 20V, V _{CE} = 0V			1	μA
V _{GE(TH)}	Gate threshold voltage	Ic = 40mA, V _{GE} = V _{CE}		5.8		V
	Collector-emitter saturation voltage	V _{GE} = 15V, I _C = 400A		2.5		V
V _{CE(sat)}		V _{GE} = 15V, I _C = 400A, T _j = 125°C		3.2		V
l _F	Diode forward current	DC		400		Α
I _{FM}	Diode maximum forward current	$t_p = 1 ms$		800		Α
	Diode forward voltage	I _F = 400A		2.9		V
VF		I _F = 400A, T _j = 125°C		3.1		V
Cies	Input capacitance	V _{CE} = 25V, V _{GE} = 0V, f = 1MHz		50		nF
Qg	Gate charge	±15V Including external C _{ge}		5		μC
Cres	Reverse transfer capacitance	V _{CE} = 25V, V _{GE} = 0V, f = 1MHz		4		nF
L _M	Module inductance			15		nΗ
RINT	Internal transistor resistance			135		μΩ
SC _{Data}	Short circuit current, I _{SC}	$T_{j} = 125^{\circ}C$, $V_{CC} = 3400V$ $t_{p} \le 10\mu s$, $V_{GE} \le 15V$ $V_{CE (max)} = V_{CES} - L^{*} x dI/dt$ IEC 60747-9		1600		A

Note:

 $^{^{\}star}$ L is the circuit inductance + L_M

ELECTRICAL CHARACTERISTICS

 $T_{case} = 25$ °C unless stated otherwise

Symbol	Parameter	Test Conditions	Min	Тур.	Max	Units
$t_{\text{d(off)}}$	Turn-off delay time	$I_{C} = 400A$ $V_{GE} = \pm 15V$ $V_{CE} = 2800V$ $R_{G(ON)} = 8.2 \Omega$ $R_{G(OFF)} = 8.2\Omega$ $C_{ge} = 68nF$ $L_{S} \sim 190nH$		2800		ns
t f	Fall time			530		ns
E _{OFF}	Turn-off energy loss			1500		mJ
t _{d(on)}	Turn-on delay time			1000		ns
tr	Rise time			160		ns
E _{ON}	Turn-on energy loss			1750		mJ
Qrr	Diode reverse recovery charge	I _F = 400A V _{CE} = 2800V dI _F /dt = 1000A/μs		450		μC
Irr	Diode reverse recovery current			350		Α
E _{rec}	Diode reverse recovery energy			750		mJ

T_{case} = 125°C unless stated otherwise

Symbol	Parameter	Test Conditions	Min	Тур.	Max	Units
t _{d(off)}	Turn-off delay time			3100		ns
t _f	Fall time	Ic = 400A V _{GF} = ±15V		560		ns
E _{OFF}	Turn-off energy loss	V _{CE} = 2800V		1300		mJ
t _{d(on)}	Turn-on delay time	$R_{G(ON)} = 8.2 \Omega$ $R_{G(OFF)} = 8.2\Omega$ $C_{ge} = 68nF$ $L_{S} \sim 190nH$		900		ns
tr	Rise time			360		ns
Eon	Turn-on energy loss			2400		mJ
Qrr	Diode reverse recovery charge	I _F = 400A		750		μC
I _{rr}	Diode reverse recovery current	V _{CE} = 2800V		380		Α
Erec	Diode reverse recovery energy	dl⊧/dt = 1000A/µs		1000		mJ

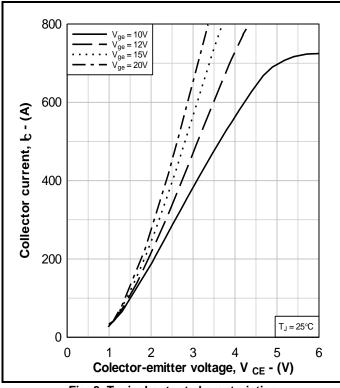


Fig. 3 Typical output characteristics

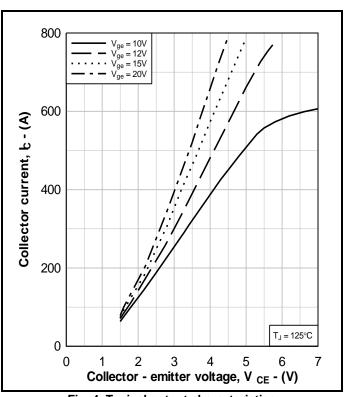


Fig. 4 Typical output characteristics

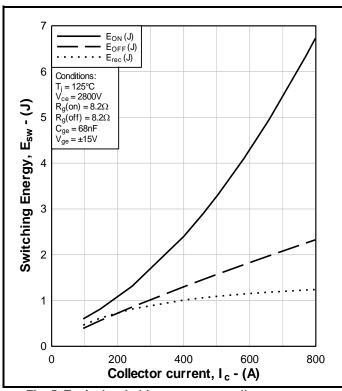


Fig. 5 Typical switching energy vs collector current

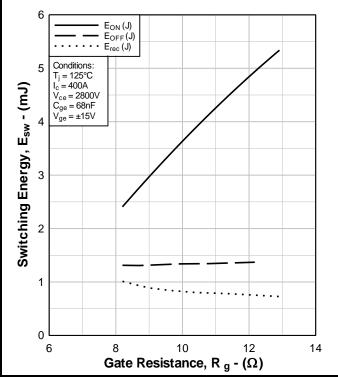


Fig. 6 Typical switching energy vs gate resistance

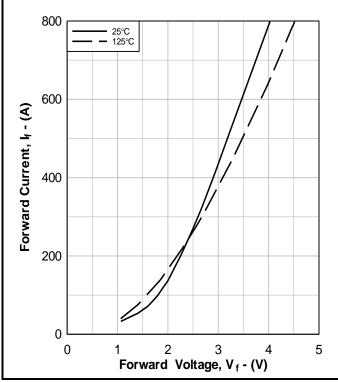


Fig. 7 Diode typical forward characteristics

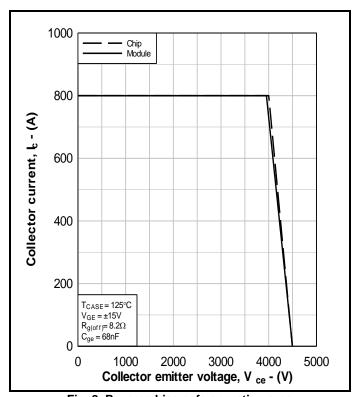


Fig. 8 Reverse bias safe operating area

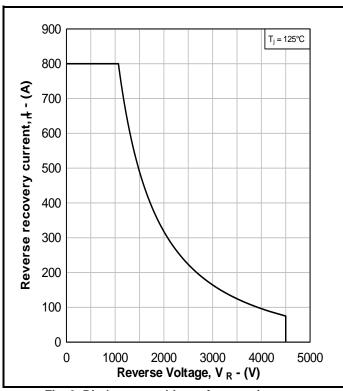


Fig. 9 Diode reverse bias safe operating area

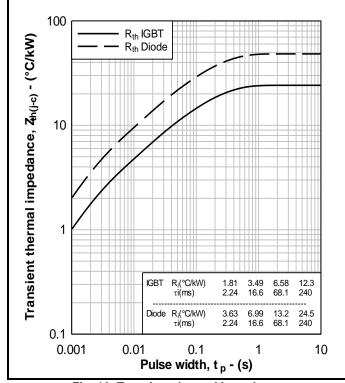


Fig. 10 Transient thermal impedance

PACKAGE DETAILS

For further package information, please visit our website or contact Customer Services. All dimensions in mm, unless stated otherwise.

DO NOT SCALE.

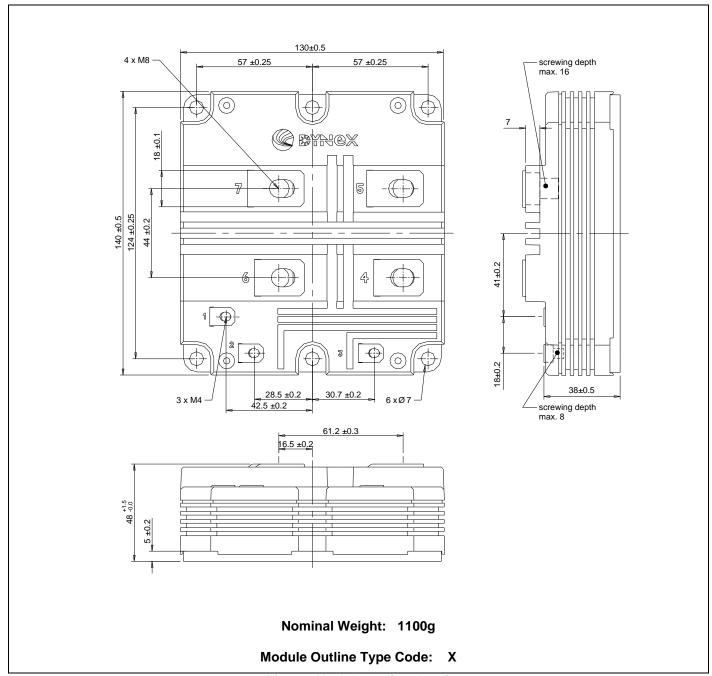


Fig. 11 Module outline drawing

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